



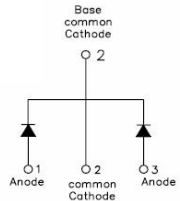
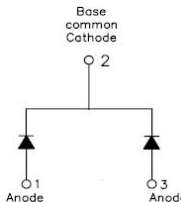
## ST3060C/STB3060C SCHOTTKY RECTIFIER

### Applications

- Switching power supply
- Converters
- Free-Wheeling diodes
- Reverse battery protection

### Features

- 150 °C T<sub>J</sub> operation
- Center tap configuration
- Ultralow forward voltage drop
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- Trench MOS Schottky technology
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

ST3060C	STB3060C
	
	
TO-220AB	D <sup>2</sup> PAK

### Maximum Ratings:

Characteristics	Symbol	Condition	Max.	Units
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	-	60	V
Average Rectified Forward Current	$I_F (AV)$	50% duty cycle @T <sub>c</sub> =100°C, rectangular wave form	15(Per Leg) 30(Per Device)	A
Peak One Cycle Non-Repetitive Surge Current(Per Leg)	$I_{FSM}$	8.3ms, Half Sine pulse	170	A

### Electrical Characteristics:

Characteristics	Symbol	Condition	Typ.	Max.	Units
Forward Voltage Drop(Per Leg)*	V <sub>F1</sub>	@ 5A, Pulse, T <sub>J</sub> = 25°C	0.42	-	V
		@ 7.5A, Pulse, T <sub>J</sub> = 25°C	0.48	-	
@ 15A, Pulse, T <sub>J</sub> = 25°C		0.59	0.70		
	V <sub>F2</sub>	@ 5A, Pulse, T <sub>J</sub> = 25°C	0.35	-	V
		@ 7.5A, Pulse, T <sub>J</sub> = 125°C	0.41	-	
		@ 15A, Pulse, T <sub>J</sub> = 125°C	0.55	0.65	
Reverse Current(Per Leg)*	I <sub>R1</sub>	@V <sub>R</sub> = rated V <sub>R</sub> , T <sub>J</sub> = 25°C	0.03	1.2	mA
	I <sub>R2</sub>	@V <sub>R</sub> = rated V <sub>R</sub> , T <sub>J</sub> = 125°C	14	45	mA
Junction Capacitance	C <sub>T</sub>	@V <sub>R</sub> = 5V, T <sub>C</sub> = 25 °C f <sub>SIG</sub> = 1MHz	712	-	pF

\* Pulse width < 300 μs, duty cycle < 2%

### Thermal-Mechanical Specifications:

Characteristics	Symbol	Condition	Specification	Units
Junction Temperature	T <sub>J</sub>	-	-55 to +150	°C
Storage Temperature	T <sub>stg</sub>	-	-55 to +150	°C
Typical Thermal Resistance Junction to Case(Per Leg)	R <sub>θJC</sub>	DC operation	2.2	°C/W

### Ratings and Characteristics Curves

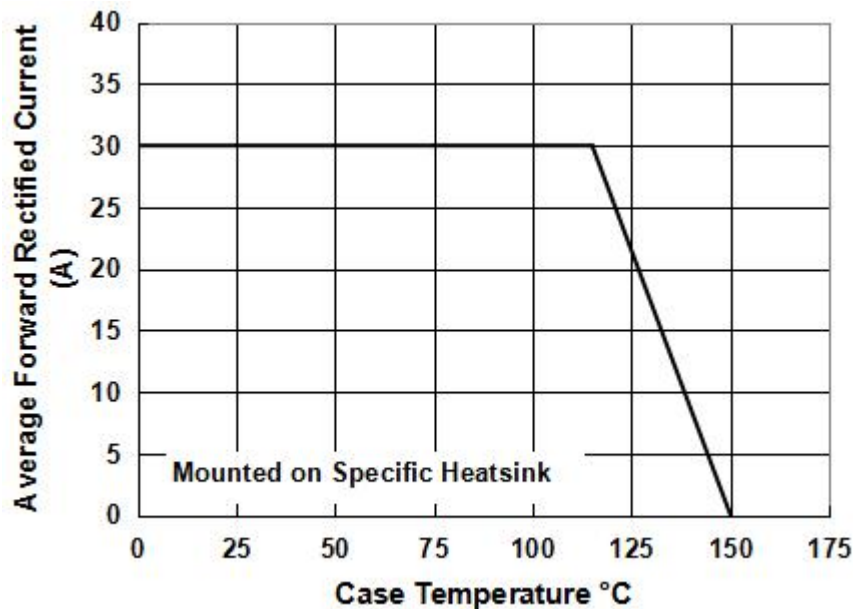


Figure 1. Maximum Forward Current Derating Curve

Figure 2  
Typical Forward Characteristics

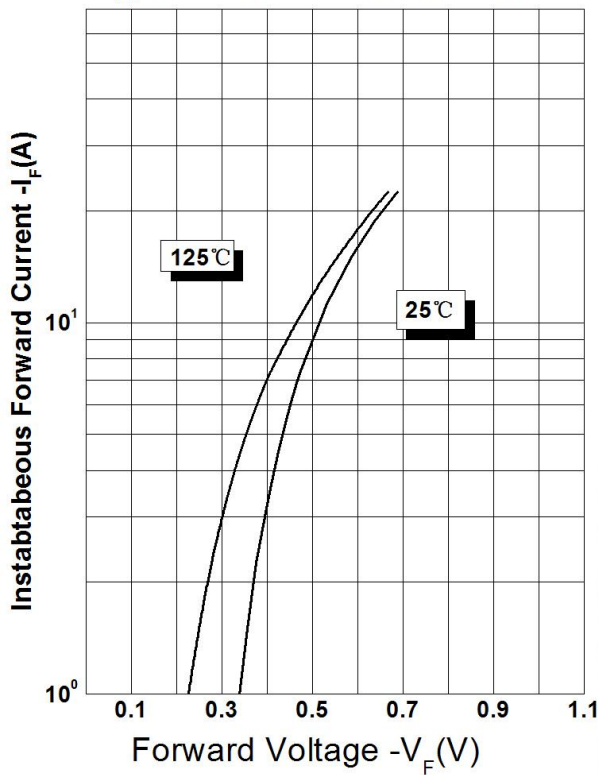


Figure 3  
Typical Reverse Characteristics

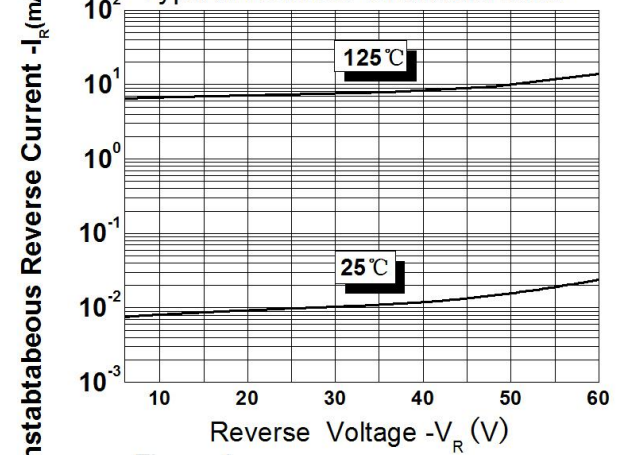
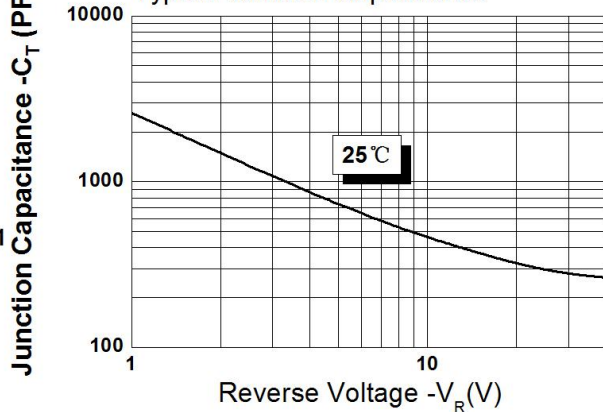


Figure 4  
Typical Junction Capacitance

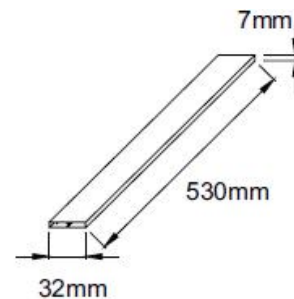


### Tube Specification

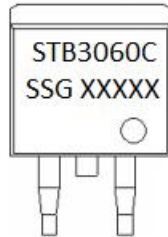
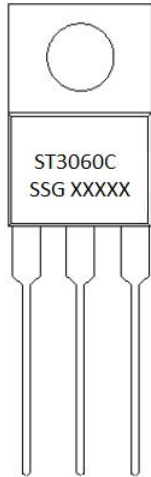
Device	Package	Weight	Shipping
ST3060C	TO-220AB	2.0	50pcs / tube
STB3060C	D <sup>2</sup> PAK	1.85	800pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

### Tube Specification(TO-220AB)



## Marking Diagram

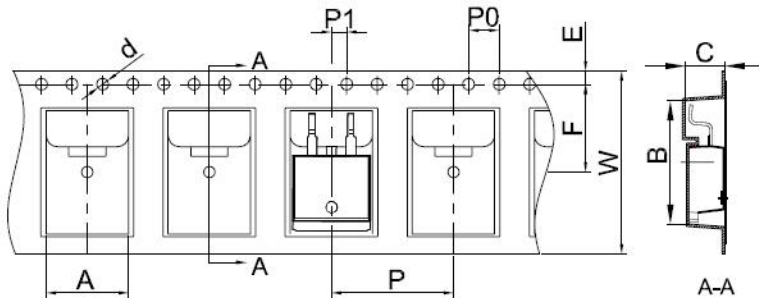


Where XXXXX is YYWWL

ST = Device Type  
 B = Package type  
 30 = Forward Current (30A)  
 60 = Reverse Voltage (60V)  
 C = Configuration  
 SSG = SSG  
 YY = Year  
 WW = Week  
 L = Lot Number

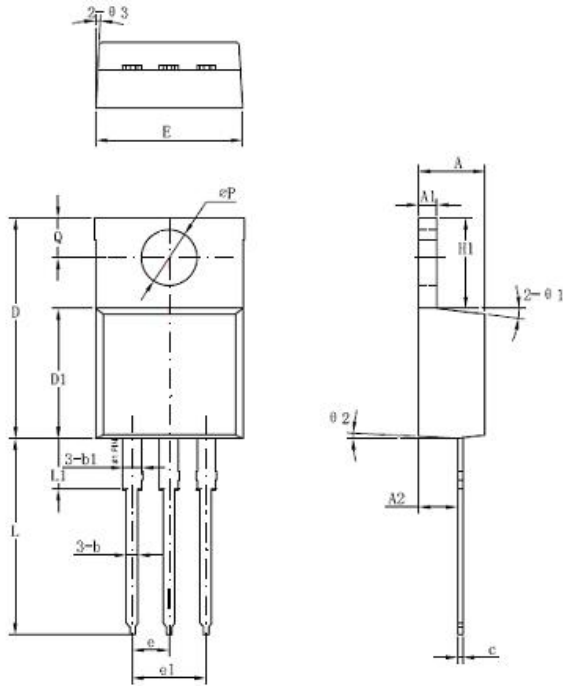
**Cautions:** Molding resin  
 Epoxy resin UL:94V-0

## Carrier Tape Specification D2PAK



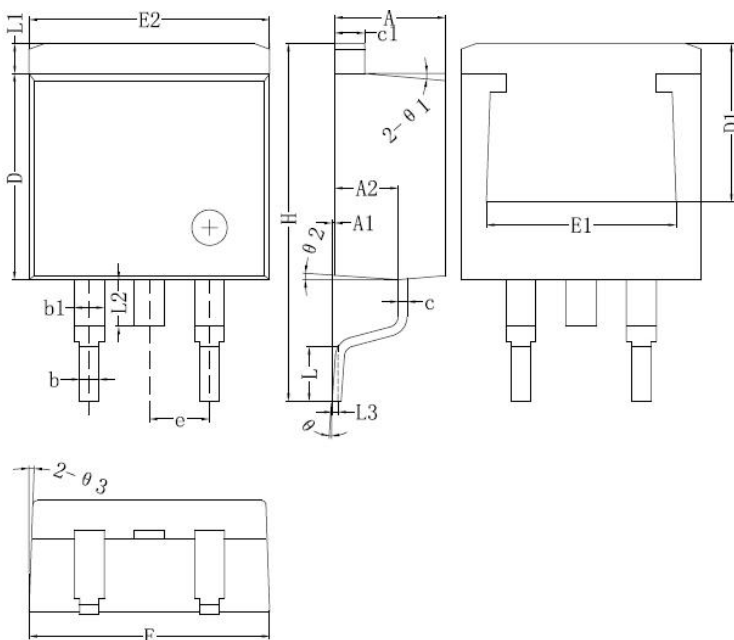
SYMBOL	Millimeters	
	Min.	Max.
A	10.70	10.90
B	16.03	16.23
C	5.11	5.31
d	1.45	1.65
E	1.65	1.85
F	11.40	11.60
P0	3.90	4.10
P	15.90	16.10
P1	1.90	2.10
W	23.90	24.30

**Mechanical Dimensions TO-220AB**



Symbol	Dimensions in millimeters		
	Min	Typical	Max
A	4.42	4.57	4.72
A1	1.17	1.27	1.37
A2	2.52	2.69	2.89
b	0.71	0.81	0.96
b1	1.17	1.27	1.37
c	0.31	0.38	0.61
D	14.94	15.24	15.54
D1	8.85	9.00	9.15
E	10.01	10.16	10.31
e		2.54	
e1	4.98	5.06	5.18
H1	6.04	6.24	6.44
L	12.7	13.56	13.80
L1	3.56	3.5	3.96
ΦP	3.74	3.84	4.04
Q	2.54	2.74	2.94
Q1		7°	
Q2		3°	
Q3		4°	

**Mechanical Dimensions D<sup>2</sup>PAK**



Symbol	Dimensions in millimeters		
	Min.	Typical	Max.
A	4.47	4.70	4.85
A1	0	0.10	0.25
A2	2.59	2.69	2.89
b	0.71	0.81	0.96
b1	1.17	1.27	1.37
c	0.31	0.38	0.61
c1	1.17	1.27	1.37
D	8.50	8.70	8.90
D1	6.40		
E	10.01	10.16	10.31
E1	7.6		
E2	9.98	10.08	10.31
e		2.54	
H	14.6	15.1	15.6
L	2.00	2.30	2.74
L1	1.12	1.27	1.42
L2	1.30		2.20
L3		0.25BSC	
e	0	-	8°
e1		5°	
e2		4°	
e3		4°	

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